MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

CPGA355, 36.10x43.10
CASE 107DJ−01
ISSUE 0

DATE 06 JUL 2011

NOTES:
2. CONTROLLING DIMENSION MILLIETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT
   DOES NOT INCLUDE HEATSPINS OR OTHER ATTACHED FEATURES.
4. DIMENSIONS D AND E DO NOT INCLUDE PROTRUSIONS. SUCH
   PROTRUSIONS SHALL NOT EXTEND MORE THAN .008 IN ANY SIDE
   CORNERS AND EDGES OF THE PACKAGE MAY HAVE CHAMBERS.
5. PIN 1 IDENTIFICATION WILL BE ON THIS AREA TO TYPE
   MAY CONSIST OF NOTCHES, METALLIZED MARKINGS, OR OTHER
   FEATURES.
6. THIS DIMENSION DEFINES THE MAXIMUM SIZE FOR THE PIN
   BRAZE PADS.

<table>
<thead>
<tr>
<th>DIM</th>
<th>MIN.</th>
<th>MAX</th>
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<tbody>
<tr>
<td>A</td>
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<td>3.85</td>
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<tr>
<td>h</td>
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<td>0.35</td>
</tr>
<tr>
<td>bE</td>
<td>.05</td>
<td>.105</td>
</tr>
<tr>
<td>D</td>
<td>25.74</td>
<td>26.46</td>
</tr>
<tr>
<td>E</td>
<td>40.67</td>
<td>43.53</td>
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<td>REF</td>
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<td>L</td>
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</tbody>
</table>

TOP VIEW

SIDE VIEW

BOTTOM VIEW

 detail A

NOTE 3

NOTE 5

DiAGRAM ON PAGE 2

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TOP OF PACKAGE

MARK THIS EDGE - ON SIDE

MARK THIS EDGE - ON SIDE

SIDE VIEW

CLASS

XXXXXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
NNNN = Serial Number